



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Timothy R. SPOONER et al. GROUP: 2829

SERIAL NO: 10/006,966

EXAMINER: S. Geyer

FILED: December 5, 2001

FOR: A METHOD AND DEVICE FOR PROTECTING MICRO  
ELECTROMECHANICAL SYSTEMS STRUCTURES  
DURING DICING OF A WAFER

Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

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RESPONSE UNDER 37 C.F.R. 1.111

In response to the Office Action mailed April 9, 2003, the following remarks are respectfully submitted under 37 C.F.R. 1.111 in connection with the above-identified application.

REMARKS

Claims 1-156 are pending in the present application.

The Examiner has alleged that the presently-pending claims are directed to three separate groups of inventions. More specifically, the Examiner alleges that: Group I is drawn to a method for protecting a MEMS structure during a dicing of a MEMS wafer to produce individual MEMS dies; Group II is drawn to a method for protecting a MEMS structure during a production of individual MEMS dies; and Group III is drawn to a laminated MEMS wafer. In view of these allegations, the Examiner has subjected claims 1-156 to a three-way restriction requirement. This restriction requirement by the Examiner is respectfully traversed.